

ABSTRACT

Provided are a pre-alignment apparatus and a method for a warped wafer. The apparatus includes an air nozzle assembly and a roller assembly. The air nozzle assembly is configured to blow air to an edge of one side of a warped wafer, and apply pressure to the edge of the one side of the warped wafer (90), so as to planarize a region of the edge of the warped wafer. The roller assembly is arranged corresponding to the air nozzle assembly along a vertical direction, and configured to, in condition that the air nozzle assembly blows the air to the warped wafer, support the edge of the warped wafer on another side of the warped wafer. The pre-alignment apparatus for a warped wafer realizes performing adsorbing positioning and planarization treatment on a large warped wafer and improves a pre-alignment precision of the large warped wafer. Correspondingly, a pre-alignment method for a warped wafer is further provided.

FIG. 1